

*ABSTRACT AMENDMENTS*

Replace the Abstract with:

~~To provide a A stem type package with good high frequency characteristics for high-speed transmission of at 10Gbps or more, the package and higher~~ includes a stem which has an under surface, an upper surface and one or more through holes penetrating from the upper surface to the under surface, a mount ~~to be mounted for mounting~~, with an optical semiconductor device, on the upper surface, a lead terminal for signal supply penetrating one of the through holes with an insulator between ~~them~~ the stem and the lead terminal, the upper surface having an earth conductor adjacent to the lead terminal for signal supply ~~projected and projecting~~ from the upper surface so that a difference between the characteristic impedance of the transmission line constituted ~~with by~~ the through hole, the insulator, and the lead terminal for signal supply and the characteristic impedance of the transmission line constituted ~~with by~~ a lead terminal for signal supply ~~projected projecting~~ from the upper surface ~~becomes~~ is small.